

This project has received funding from the European Union's Horizon 2020 Research and Innovation programme under GA No 101004730.

Millisecond flash lamp treatment for SRF accelerating cavities



IIF Evaluation - CERN 16 November 2022

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Cristian Pira - Millisecond flash lamp treatment for SRF accelerating cavities - IIF Evauation

Nb₃Sn State of the art

Nb₃Sn on Nb by Tin Vapour Diffusion already show performances at 4.2 K comparable to bulk Nb at 2K

Nb cavity as substrate:

expensive

FAST

 Bad thermal conductivity (strong limitation for industrial applications that require Cryocoolers)



S. Posen, SRF 2019 proceedings (elaborated)

Nb₃Sn on Cu by Sputtering

- Similar to Nb on Cu cavities
- Solve the Low Thermal Conductivity issue of Nb substrate
- A first prototype of 1.3 GHz cavity is under developing in **iFAST WP9**
- Low melting point of Cu is a limitation
- 650 °C can be considered a limit in a Cu cavity
- Diffusion of Cu into Nb₃Sn

FAST



6 GHz Nb on Cu Cavity @LNL

Nb₃Sn on Cu by Sputtering

- Nb₃Sn coating Tc increase with substrate temperature deposition (Stewart Leith CERN, TFSRF JLab 2022), (Pira INFN, TFSRF JLab 2022)
- Optimal T seems ~950 °C → Tc= 17.9 K (in Nb₃Sn on Nb by sputtering) (Nizam Sayeed - Jlab, SRF 2021)







Develop a novel thermal process to improve performances of SC coating by suppressing (reducing) Cu substrate heating

Millisecond-flash-lamp-annealing (FLA)



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Millisecond-flash-lamp-annealing (FLA)



FLA Advantages compared to standard annealing

- FLA is an innovative process for thermal pre- and post-treatment of functional coatings and sensitive substrates in millisecond range time scale.
- The thermal load and hence the temperature throughout the entire substrate is much lower compared to conventional annealing.
 This produces two advantages in respect to standard annealing (state of the art for sputtering processes):
 - 1. Suppresses the diffusion of Cu into SC layer
 - A diffusion barrier (Nb or Ta film) between Nb₃Sn and Cu may **no longer be needed**
 - 2. Higher annealing temperature possible on SC coating

On Nb₃Sn we expect an **improvement of Tc** from 10-16 K to 18 K~

Tc range for Nb₃Sn on Cu with ' standard annealing up to 650 °C





Pulse length – 0.4 - 23 ms Max. E = 145 Jcm⁻² Sample size – 12" or 40x40cm



Tc of Nb₃Sn on Nb by sputtering annealed at 950°C



How to implement in a cavity?



Proof of concept

Recrystallization of magnetron sputtered TiO₂ thin film on Si-substrate With FLA grain dimension enhancement and lower roughness





Flash Lamp Annealing 120 Jcm⁻² 20 ms



Courtesy of Raul Gago (CSIC Madrid, Spain)

FLA reduce diffusion of dopants in semiconductors compared with standard annealing





FIRST TEST ON SC SAMPLE

2 micron Nb-NbN multy layer on Cu substrate coated by STFC

2.2 ms FLA treatment

The FLA produce a narrower hysteresis curve (material crystallinity improved)



Expected results (technology validation)

- On planar samples:
 - 1. Nb on Cu: grain size enlargement of Nb, Cu substrate almost unaffected
 - 2. improvement of the Tc up to 18 K in Nb₃Sn on Cu films
- On 6 GHz cavities:
 - **3. treatment uniformity** along the cavity (check by grain size measurement on Nb and on Cu cavity)
 - 4. Q value of 1*10° at 4.2 K for Nb₃Sn on Cu 6 GHz cavity by RF test (same performances of Nb at 2 K)

Point 4 success strongly depend on iFAST task 9.3





Budget

| | REQUEST | MOTIVATION | COST |
|-----|---------------------------|----------------------|---------|
| R | Personnel costs | 2 year person | 96 500 |
| RUM | Equipment and consumables | FLA system for 6 GHz | 13 500 |
| | TOTAL | | 110 000 |

| REQUEST | MOTIVATION | COST |
|---------------------------|--------------------------|--------|
| Personnel costs | iFAST contract extension | 20 000 |
| Equipment and consumables | Targets, Helium, samples | 20 000 |
| TOTAL | 40 000 | |

| | REQUEST | MOTIVATION | COST |
|------------------------------|---------------------------|--------------------------|--------|
| MPICCOU. | Personnel costs | iFAST contract extension | 3 000 |
| TORNERIA IN LASTRA HETALLICA | Equipment and consumables | Cavities production | 7 000 |
| | TOTAL | | 10 000 |

| Co-funding | MOTIVATION | COST |
|------------|---------------------|--------|
| Personnel | 6 months researcher | 50 000 |
| | Helium, Lamps | 20 000 |
| TOTAL | | 70 000 |

| Co-funding | MOTIVATION | COST |
|------------|---------------------|--------|
| Personnel | 6 months researcher | 30 000 |
| TOTAL | 30 000 | |

TOTAL CO-FUNDING 100 k€ (Funding rate = 0.49)

TOTAL BUDGET REQUEST 160 k€



HZD HELMHOLTZ ZEN DRESDEN ROSSE

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• A working 6 GHz cavity can be considered as **TRL4**

• To reach TRL6 process must be scaled to 1.3 GHz cavity.

- FLA scaling is not critical, but first must be demonstrated the possibility to coat Nb3Sn on a 1.3 GHz cavity (final goal of iFAST task 9.2, expected in 2025)
- 2027-2030 can be a reasonable date

2 Addressable Markets

1) SRF Cavities

FAST

High Energy Particle Accelerators

Companies like Zanon Research & Innovation Srl and RI Research Instruments GmbH, which work in synergy with large international laboratories are potential end users of our technology

• New industrial Applications of SRF cavities

- Nb₃Sn on Cu allows cryocooler cooling by eliminating complex and expensive cryogenics
- Conduction-cooled SRF accelerator can move SRF to industrial application (proof of concepts ongoing in USA):
 - Treat Municipal Waste & Sludge (Eliminate pathogens in sludge, destroy organics, and pharmaceuticals in wastewater)
 - In-situ cross-link of materials
 - Medical sterilization without Co60



Jayakar Thangaraj (Fermilab), TTC 2022 Aomori



2 Addressable Markets

2) FLASH LAMP ANNEALING

Flash lamp annealing can be applied to numerous applications



Activation of anticorrosion coatings



Improving the tribological properties of biocompatible implants



Sustainability

Our technology will significantly **reduce the environmental impact** and **energy-costs** of SRF accelerator technology:

- The goal is to realize SC resonant cavities operating at higher T than bulk Nb reducing cryogenic power costs by 60%
- The thermal load and hence the temperature throughout the entire substrate is much lower compared to conventional annealing: FLA is less energy-intensive (20-30% power reduction (1), resulting in a reduction of CO₂ emissions



(1) Rovak GmbH experience on Semiconductors





Thank you



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